

(1,00mm) .03937"

MEC1 SERIES

MEC1-120-02-F-D-A

MEC1-130-02-F-D-A

MEC1-140-02-L-D

MINI EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC1

Insulator Material: Black LCP

Contact Material: BeCu

Plating: Sn or Au over 50µ"

(1,27µm) Ni

Operating Temp Range: -55°C to +125°C

Current Rating: 2A @ 80°C ambient

(See website for details)

Voltage Rating: 300 VAC

Insertion Depth: (5,84mm) .230" to

(8,13mm) .320"

RoHS Compliant: Yes

Processing: Lead-Free Solderable:

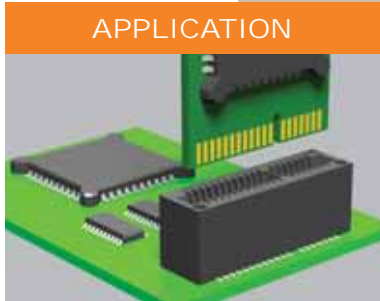
Yes

SMT Lead Coplanarity: (0,10mm) .004" max (05-20)

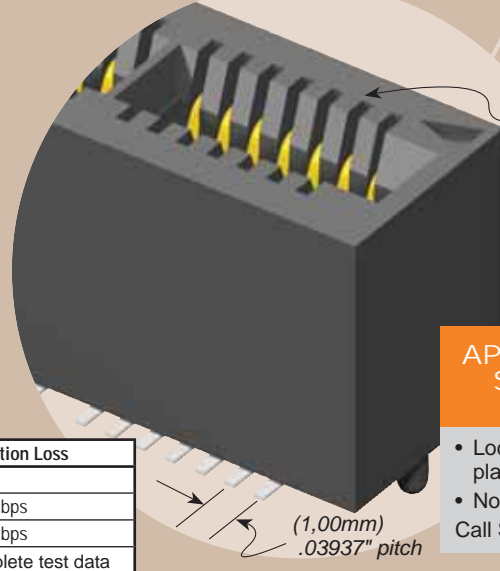
(0,15mm) .006" max (30-70)



Mates with: (1,60mm) .062" card



APPLICATION



Mates with (1,60mm) .062" card

APPLICATION SPECIFIC OPTION

- Locking Clip (Manual placement required).
- Non-polarized Call Samtec.

1mm MEC1	Rated @ -3dB Insertion Loss
9,19mm Stack Height	
Single-Ended Signaling	5.5 GHz / 11 Gbps
Differential Pair Signaling	6.5 GHz / 13 Gbps

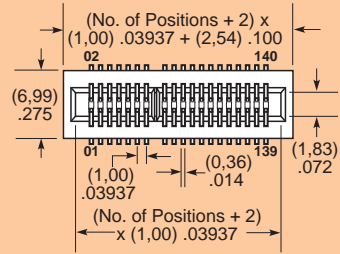
Performance data for other stack heights and complete test data available at www.samtec.com?MEC1 or contact sig@samtec.com

MEC1 - 1 POSITIONS PER ROW - 02 - PLATING OPTION - D - OTHER OPTION

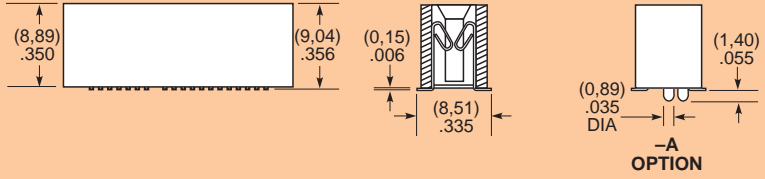
05, 08, 20, 30, 40, 50, 60, 70

- F = Gold flash on contact, Matte tin on tail
- L = 10µ" (0,25µm) Gold on contact, Matte Tin on tail

- A = Alignment Pin metal or plastic at Samtec discretion.
- K = (7,87mm) .310" DIA Polyimide film Pick & Place Pad
- TR = Tape & Reel



POSITIONS PER ROW	POLARIZED POSITIONS (No Contact)
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116



Note: Other Gold plating options available. Contact Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM